

# 256 x 8 Bit

# SPI Serial E<sup>2</sup>PROM with Block Lock<sup>™</sup> Protection

#### FEATURES

**2K** 

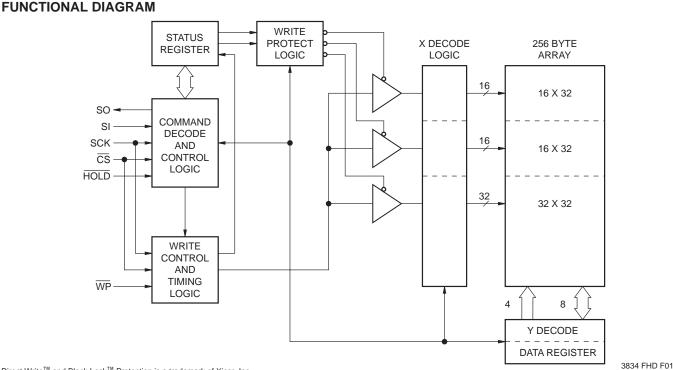
- 1MHz Clock Rate
- SPI Modes (0,0 & 1,1)
- 256 X 8 Bits
   4 Byte Bat
- -4 Byte Page Mode • Low Power CMOS
- 2.7V To 5.5V Power Supply
- Block Lock Protection —Protect 1/4, 1/2 or all of E<sup>2</sup>PROM Array
- Built-in Inadvertent Write Protection —Power-Up/Power-Down protection circuitry —Write Latch
  - —Write Protect Pin
- Self-Timed Write Cycle —5ms Write Cycle Time (Typical)
- High Reliability —Endurance: 100,000 cycles per byte —Data Retention: 100 Years
  - -ESD protection: 2000V on all pins
- 8-Lead PDIP Package
- 8-Lead SOIC Package

# DESCRIPTION

The X25020 is a CMOS 2048-bit serial E<sup>2</sup>PROM, internally organized as 256 x 8. The X25020 features a serial interface and software protocol allowing operation on a simple three-wire bus. The bus signals are a clock input (SCK) plus separate data in (SI) and data out (SO) lines. Access to the device is controlled through a chip select ( $\overline{CS}$ ) input, allowing any number of devices to share the same bus.

The X25020 also features two additional inputs that provide the end user with added flexibility. By asserting the  $\overline{HOLD}$  input, the X25020 will ignore transitions on its inputs, thus allowing the host to service higher priority interrupts. The  $\overline{WP}$  input can be used as a hardwire input to the X25020 disabling all write attempts, thus providing a mechanism for limiting end user capability of altering the memory.

The X25020 utilizes Xicor's proprietary Direct Write<sup>™</sup> cell, providing a minimum endurance of 100,000 cycles per byte and a minimum data retention of 100 years.



Direct Write<sup>™</sup> and Block Lock<sup>™</sup> Protection is a trademark of Xicor, Inc.

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#### **PIN DESCRIPTIONS**

#### Serial Output (SO)

SO is a push/pull serial data output pin. During a read cycle, data is shifted out on this pin. Data is clocked out by the falling edge of the serial clock.

#### Serial Input (SI)

SI is the serial data input pin. All opcodes, byte addresses, and data to be written to the memory are input on this pin. Data is latched by the rising edge of the serial clock.

#### Serial Clock (SCK)

The Serial Clock controls the serial bus timing for data input and output. Opcodes, addresses, or data present on the SI pin are latched on the rising edge of the clock input, while data on the SO pin change after the falling edge of the clock input.

#### Chip Select (CS)

When  $\overline{CS}$  is HIGH, the X25020 is deselected and the SO output pin is at high impedance and unless an internal write operation is underway, the X25020 will be in the standby power mode.  $\overline{CS}$  LOW enables the X25020, placing it in the active power mode. It should be noted that after power-up, a HIGH to LOW transition on  $\overline{CS}$  is required prior to the start of any operation.

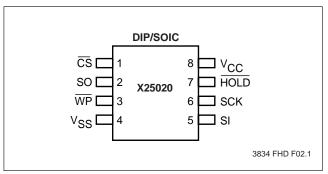
### Write Protect (WP)

When  $\overline{WP}$  is LOW, nonvolatile writes to the X25020 are disabled, but the part otherwise functions normally. When  $\overline{WP}$  is held HIGH, all functions, including nonvolatile writes operate normally.  $\overline{WP}$  going LOW while  $\overline{CS}$  is still LOW will interrupt a write to the X25020. If the internal write cycle has already been initiated,  $\overline{WP}$  going LOW will have no affect on a write.

## Hold (HOLD)

HOLD is used in conjunction with the CS pin to select the device. Once the part is selected and a serial sequence is underway, HOLD may be used to pause the serial communication with the controller without resetting the serial sequence. To pause, HOLD must be brought LOW while SCK is LOW. To resume communication, HOLD is brought HIGH, again while SCK is LOW. If the pause feature is not used, HOLD should be held HIGH at all times.

#### **PIN CONFIGURATION**



#### **PIN NAMES**

Description			
Chip Select Input			
Serial Output			
Serial Input			
Serial Clock Input			
Write Protect Input			
Ground			
Supply Voltage			
Hold Input			

3834 PGM T01.1

#### PRINCIPLES OF OPERATION

The X25020 is a 256 x 8  $E^2$ PROM designed to interface directly with the synchronous serial peripheral interface (SPI) of many popular microcontroller families.

The X25020 contains an 8-bit instruction register. It is accessed via the SI input, with data being clocked in on the rising SCK. CS must be LOW and the HOLD and WP inputs must be HIGH during the entire operation.

Table 1 contains a list of the instructions and their opcodes. All instructions, addresses and data are transferred MSB first.

Data input is sampled on the first rising edge of SCK after  $\overline{CS}$  goes LOW. SCK is static, allowing the user to stop the clock and then resume operations. If the clock line is shared with other peripheral devices on the SPI bus, the user can assert the HOLD input to place the X25020 into a "PAUSE" condition. After releasing HOLD, the X25020 will resume operation from the point when HOLD was first asserted.

#### Write Enable Latch

The X25020 contains a "write enable" latch. This latch must be SET before a write operation will be completed internally. The WREN instruction will set the latch and the WRDI instruction will reset the latch. This latch is automatically reset upon a power-up condition and after the completion of a byte, page, or status register write cycle.

#### **Status Register**

The RDSR instruction provides access to the status register. The status register may be read at any time, even during a write cycle. The status register is formatted as follows:

7	6	5	4	3	2	1	0
Х	Х	Х	Х	BP1	BP0	WEL	WIP
						3	834 PGM T02

BP0 and BP1 are set by the WRSR instruction. WEL and WIP are read-only and automatically set by other operations.

The Write-In-Process (WIP) bit indicates whether the X25020 is busy with a write operation. When set to a "1", a write is in progress, when set to a "0", no write is in progress. During a write, all other bits are set to "1".

The Write Enable Latch (WEL) bit indicates the status of the "write enable" latch. When set to a "1", the latch is set, when set to a "0", the latch is reset.

The Block Protect (BP0 and BP1) bits are nonvolatile and allow the user to select one of four levels of protection. The X25020 is divided into four 512-bit segments. One, two, or all four of the segments may be protected. That is, the user may read the segments but will be unable to alter (write) data within the selected segments. The partitioning is controlled as illustrated below.

Status Re	gister Bits	Array Addresses
BP1	BP0	Protected
0	0	None
0	1	\$C0\$FF
1	0	\$80–\$FF
1	1	\$00–\$FF

3834 PGM T03

Instruction Name	Instruction Format*	Operation
WREN	0000 0110	Set the Write Enable Latch (Enable Write Operations)
WRDI	0000 0100	Reset the Write Enable Latch (Disable Write Operations)
RDSR	0000 0101	Read Status Register
WRSR	0000 0001	Write Status Register
READ	0000 0011	Read Data from Memory Array beginning at selected address
WRITE	0000 0010	Write Data to Memory Array beginning at Selected Address (1 to 32 Bytes)

 Table 1. Instruction Set

\*Instructions are shown MSB in leftmost position. Instructions are transferred MSB first.

#### **Clock and Data Timing**

Data input on the SI line is latched on the rising edge of SCK. Data is output on the SO line by the falling edge of SCK.

#### **Read Sequence**

When reading from the E<sup>2</sup>PROM memory array,  $\overline{CS}$  is first pulled LOW to select the device. The 8-bit READ instruction is transmitted to the X25020, followed by the 8-bit address. After the READ opcode and address are sent, the data stored in the memory at the selected address is shifted out on the SO line. The data stored in memory at the next address can be read sequentially by continuing to provide clock pulses. The address is automatically incremented to the next higher address after each byte of data is shifted out. When the highest address is reached (\$FF) the address counter rolls over to address \$00 allowing the read cycle to be continued indefinitely. The read operation is terminated by taking  $\overline{CS}$  HIGH. Refer to the read E<sup>2</sup>PROM array operation sequence illustrated in Figure 1.

To read the status register  $\overline{CS}$  line is first pulled LOW to select the device followed by the 8-bit RDSR instruction. After the read status register opcode is sent, the contents of the status register are shifted out on the SO line. Figure 2 illustrates the read status register sequence.

### Write Sequence

Prior to any attempt to write data into the X25020 the "write enable" latch must first be set by issuing the WREN instruction (See Figure 3).  $\overline{CS}$  is first taken LOW, then the WREN instruction is clocked into the X25020. After all eight bits of the instruction are transmitted,  $\overline{CS}$  must then be taken HIGH. If the user continues the write operation without taking  $\overline{CS}$  HIGH after issuing the WREN instruction, the write operation will be ignored.

To write data to the E<sup>2</sup>PROM memory array, the user issues the WRITE instruction, followed by the address and then the data to be written. This is minimally a thirty-two clock operation.  $\overline{CS}$  must go LOW and remain LOW for the duration of the operation. The host may continue to write up to 4 bytes of data to the X25020. The only restriction is that the 4 bytes must reside on the same page. If the address counter reaches the end of the page and the clock continues, the counter will "roll over" to the first address of the page and overwrite any data that may have been written.

For the write operation (byte or page write) to be completed,  $\overline{CS}$  can only be brought HIGH after bit 0 of data byte N is clocked in. If it is brought HIGH at any other time the write operation will not be completed. Refer to Figures 4 and 5 below for a detailed illustration of the write sequences and time frames in which  $\overline{CS}$  going HIGH are valid.

To write to the status register, the WRSR instruction is followed by the data to be written. Data bits 0, 1, 4, 5, 6 and 7 must be "0". Figure 6 illustrates this sequence.

While the write is in progress following a status register or  $E^2PROM$  write sequence, the status register may be read to check the WIP bit. During this time the WIP bit will be HIGH.

#### **Hold Operation**

The  $\overline{\text{HOLD}}$  input should be HIGH (at V<sub>IH</sub>) under normal operation. If a data transfer is to be interrupted  $\overline{\text{HOLD}}$  can be pulled LOW to suspend the transfer until it can be resumed. The only restriction is the SCK input must be LOW when  $\overline{\text{HOLD}}$  is first pulled LOW and SCK must also be LOW when  $\overline{\text{HOLD}}$  is released.

The HOLD input may be tied HIGH either directly to  $V_{CC}$  or tied to  $V_{CC}$  through a resistor.

#### **Operational Notes**

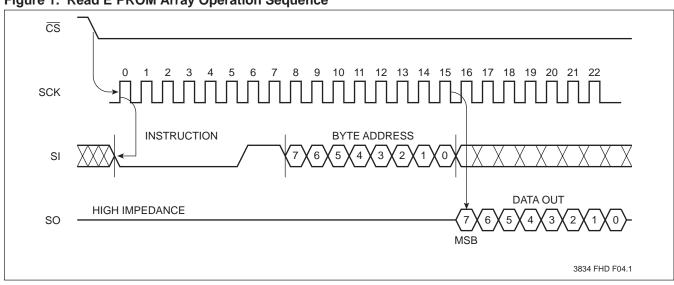
The X25020 powers-up in the following state:

- The device is in the low power standby state.
- A HIGH to LOW transition on  $\overline{CS}$  is required to enter an active state and receive an instruction.
- SO pin is high impedance.
- The "write enable" latch is reset.

#### **Data Protection**

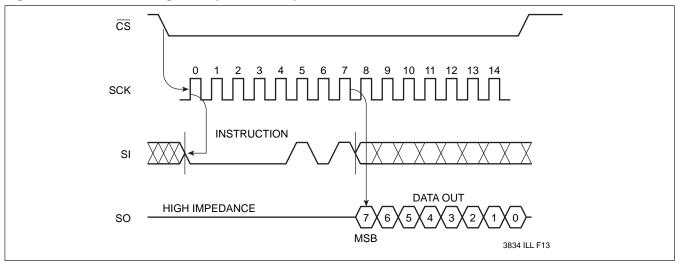
The following circuitry has been included to prevent inadvertent writes:

- The "write enable" latch is reset upon power-up.
- A WREN instruction must be issued to set the "write enable" latch.
- CS must come HIGH at the proper clock count in order to start a write cycle.



#### Figure 1. Read E<sup>2</sup>PROM Array Operation Sequence

Figure 2. Read Status Register Operation Sequence



#### Figure 3. Write Enable Latch Sequence

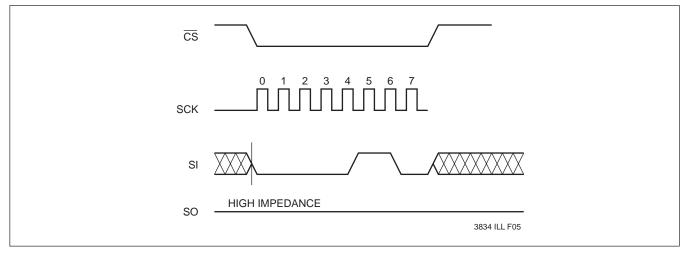
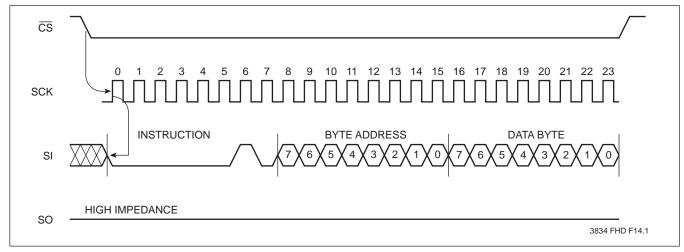
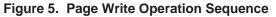
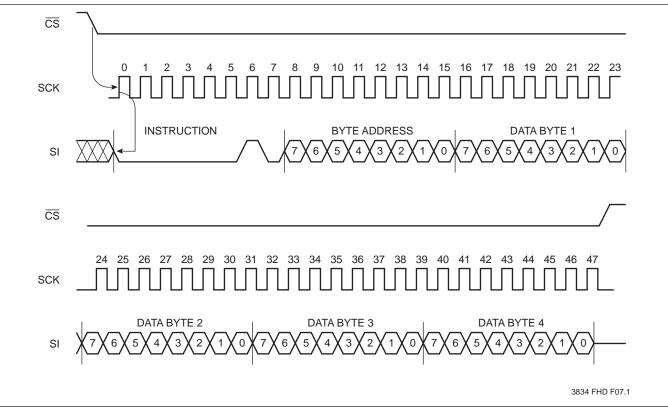


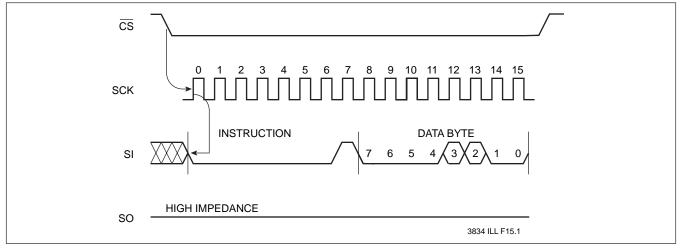
Figure 4. Byte Write Operation Sequence











#### **ABSOLUTE MAXIMUM RATINGS\***

Temperature under Bias –65°C to +135°C
Storage Temperature –65°C to +150°C
Voltage on any Pin with Respect to $V_{SS}$ 1V to +7V
D.C. Output Current5mA
Lead Temperature
(Soldering, 10 seconds) 300°C

#### **\*COMMENT**

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and the functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **RECOMMENDED OPERATING CONDITIONS**

Temp	Min.	Max.
Commercial	0°C	+70°C
Industrial	_40°C	+85°C
6.		3834 PGM T05.2

Supply Voltage	Limits
X25020	5V ±10%
X25020–3	3V to 5.5V
X25020–2.7	2.7V to 5.5V
	3834 PGM T06.1

D.C. OPERATING CHARACTERISTICS (Over the recommended operating conditions unless otherwise specified.)

		Limits			
Symbol	Parameter	Min.	Max.	Units	Test Conditions
ICC	V <sub>CC</sub> Supply Current (Active)		3	mA	SCK = V <sub>CC</sub> x 0.1/V <sub>CC</sub> x 0.9 @ 1MHz, SO = Open
I <sub>SB</sub>	V <sub>CC</sub> Supply Current (Standby)		10	μA	$\overline{\text{CS}} = \text{V}_{\text{CC}}, \text{ V}_{\text{IN}} = \text{V}_{\text{SS}} \text{ or } \text{V}_{\text{CC}} - 0.3 \text{V}$
ILI	Input Leakage Current		10	μΑ	$V_{IN} = V_{SS}$ to $V_{CC}$
ILO	Output Leakage Current		10	μΑ	$V_{OUT} = V_{SS}$ to $V_{CC}$
V <sub>IL</sub> <sup>(1)</sup>	Input LOW Voltage	-0.5	V <sub>CC</sub> x 0.3	V	
VIH <sup>(1)</sup>	Input HIGH Voltage	V <sub>CC</sub> x 0.7	V <sub>CC</sub> + 0.5	V	
VOL	Output LOW Voltage		0.4	V	$I_{OL} = 2mA$
VOH	Output HIGH Voltage	V <sub>CC</sub> – 0.8		V	I <sub>OH</sub> = -1mA

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#### **POWER-UP TIMING**

Symbol	Parameter	Min.	Max.	Units
t <sub>PUR</sub> <sup>(2)</sup>	Power-up to Read Operation		1	ms
t <sub>PUW</sub> <sup>(2)</sup>	Power-up to Write Operation		5	ms

3834 PGM T08

#### **CAPACITANCE** $T_A = +25^{\circ}C$ , f = 1MHz, $V_{CC} = 5V$ .

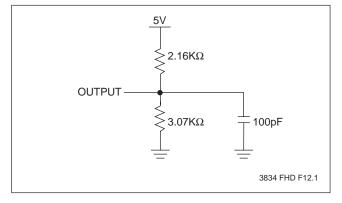
Symbo	bl	Test	Max.	Units	Conditions
C <sub>OUT</sub> (2	2)	Output Capacitance (SO)	8	pF	$V_{OUT} = 0V$
C <sub>IN</sub> <sup>(2)</sup>		Input Capacitance (SCK, SI, CS, WP, HOLD)	6	pF	$V_{IN} = 0V$
					0004 DOM T00 4

3834 PGM T09.1

Notes: (1)  $V_{IL}$  min. and  $V_{IH}$  max. are for reference only and are not tested.

(2) This parameter is periodically sampled and not 100% tested.

## EQUIVALENT A.C. LOAD CIRCUIT AT 5V V<sub>CC</sub>



#### A.C. TEST CONDITIONS

Input Pulse Levels	V <sub>CC</sub> x 0.1 to V <sub>CC</sub> x 0.9
Input Rise and Fall Times	10ns
Input and Output Timing Level	V <sub>CC</sub> x 0.5

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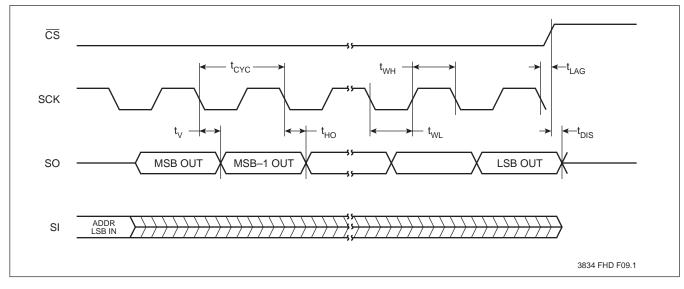
Symbol	Parameter	Min.	Max.	Units
fSCK	Clock Frequency	0	1	MHz
tCYC	Cycle Time	1000		ns
t <sub>LEAD</sub>	CS Lead Time	500		ns
t <sub>LAG</sub>	CS Lag Time	500		ns
twH	Clock HIGH Time	400		ns
twL	Clock LOW Time	400		ns
tsu	Data Setup Time	100		ns
tH	Data Hold Time	100		ns
t <sub>RI</sub>	Data In Rise Time		2	μs
t <sub>FI</sub>	Data In Fall Time		2	μs
tHD	HOLD Setup Time	200		ns
t <sub>CD</sub>	HOLD Hold Time	200		ns
t <sub>CS</sub>	CS Deselect Time	500		ns
t <sub>WC</sub> <sup>(3)</sup>	Write Cycle Time		10	ms

# **Data Output Timing**

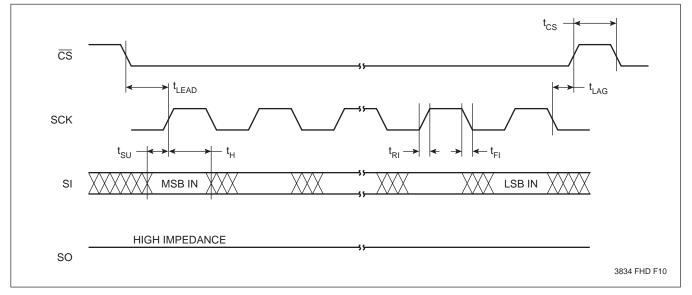
Symbol	Parameter	Min.	Max.	Units
fSCK	Clock Frequency 0		1	MHz
tDIS	Output Disable Time		500	ns
t <sub>V</sub>	Output Valid from Clock LOW	Output Valid from Clock LOW		ns
tHO	Output Hold Time	t Hold Time 0		ns
t <sub>RO</sub>	Output Rise Time	utput Rise Time		ns
t <sub>FO</sub>	Output Fall Time	t Fall Time		ns
t <sub>LZ</sub>	HOLD HIGH to Output in Low Z	H to Output in Low Z 100		ns
t <sub>HZ</sub>	HOLD LOW to Output in High Z	D LOW to Output in High Z 100		ns
I				3834 PGM T12.

Notes: (3) t<sub>WC</sub> is the time from the rising edge of  $\overline{CS}$  after a valid write sequence has been sent to the end of the self-timed internal nonvolatile write cycle.

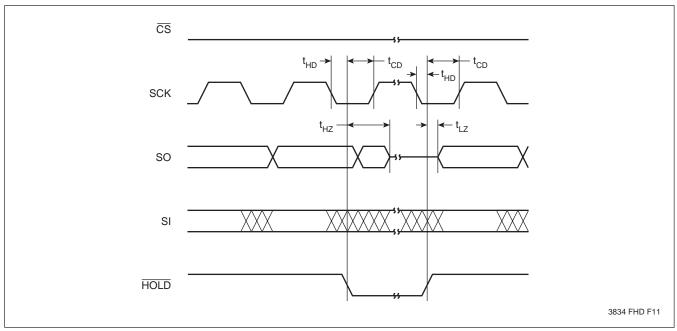
### **Serial Output Timing**



### **Serial Input Timing**



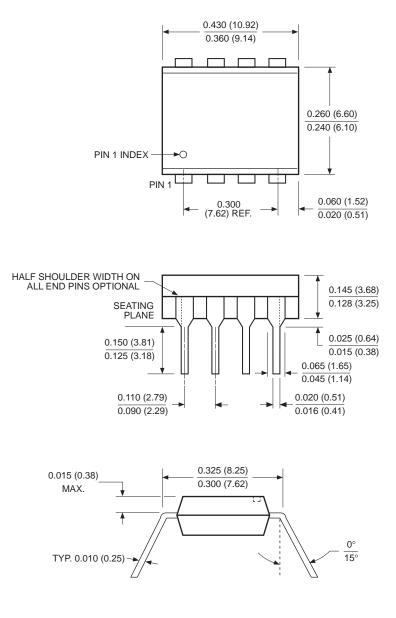
# Hold Timing



# SYMBOL TABLE

WAVEFORM	INPUTS	OUTPUTS
	Must be steady	Will be steady
	May change from LOW to HIGH	Will change from LOW to HIGH
	May change from HIGH to LOW	Will change from HIGH to LOW
	Don't Care: Changes Allowed	Changing: State Not Known
	N/A	Center Line is High Impedance

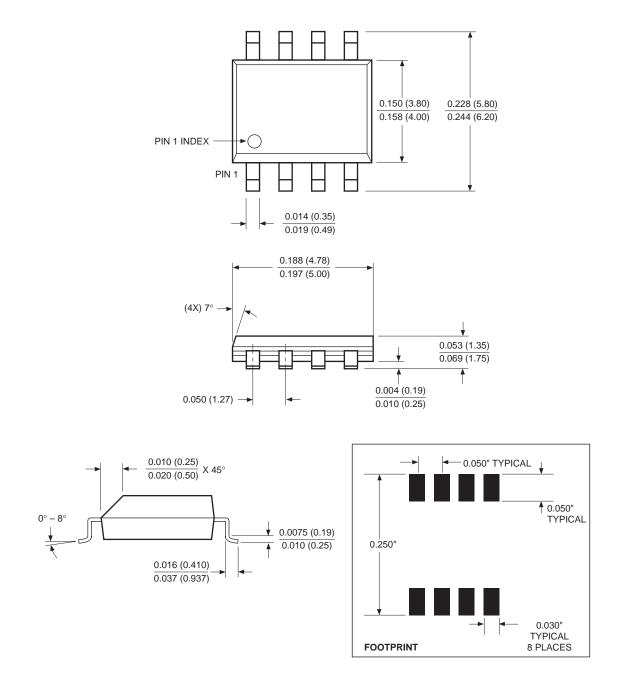
#### **PACKAGING INFORMATION**



#### 8-LEAD PLASTIC DUAL IN-LINE PACKAGE TYPE P



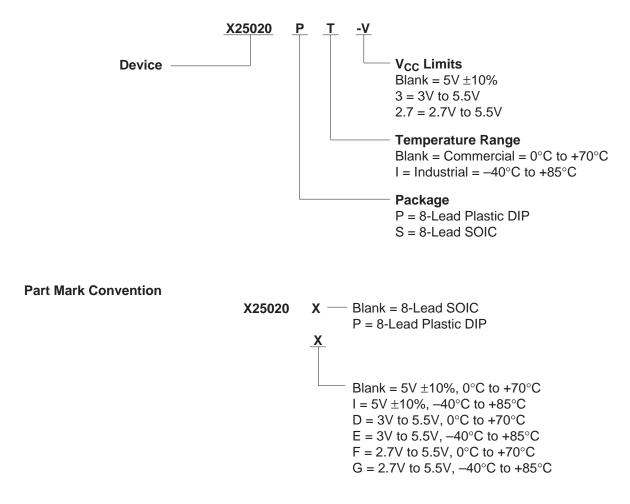
### PACKAGING INFORMATION



#### 8-LEAD PLASTIC SMALL OUTLINE GULL WING PACKAGE TYPE S

NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

#### **ORDERING INFORMATION**



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#### LIFE RELATED POLICY

In situations where semiconductor component failure may endanger life, system designers using this product should design the system with appropriate error detection and correction, redundancy and back-up features to prevent such an occurence.

Xicor's products are not authorized for use in critical components in life support devices or systems.

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.